

**Market Forecast Report**  
**Semiconductor and FPD Manufacturing Equipment**  
**Released in January 2026**  
**(Fiscal years 2025 to 2027)**

**January 15, 2026**

**SEAJ**

**Semiconductor Equipment Association of Japan**

## Overview

This report provides trend forecasts for semiconductor and FPD manufacturing equipment. The comprehensive results included in this forecast report are based on demand forecasts by the Semiconductor Research and Statistics subcommittee and the FPD Research and Statistics subcommittee of the Semiconductor Equipment Association of Japan (hereinafter called SEAJ, Chairman: Mr. Toshiki Kawai) as well as market trend research by the 20 companies represented on the Board of Directors and auditors.

We forecast sales of semiconductor manufacturing equipment made in Japan for fiscal 2025 to be 4.91 trillion yen, an increase of 3% from the previous year, due to full-scale 2 nm (GAA) investment by Taiwanese foundries and firm investment in DRAM, particularly High Bandwidth Memory (HBM). For fiscal 2026, we forecast sales of 5.50 trillion yen, an increase of 12%, driven by continued expansion in DRAM investment and expected growth in advanced logic for AI servers. For fiscal 2027, we forecast sales of 5.61 trillion yen, an increase of 2%, amid demand for AI-related products that are expected to remain high.

As for FPD manufacturing equipment, while Organic Light Emitting Diode (OLED) investments using G8.6-class boards commenced in South Korea and China during fiscal 2025, after carefully reviewing the timing of sales recognition through March, we forecast sales of 349 billion yen in fiscal 2025, an increase of 3%. For fiscal 2026, we forecast sales to remain flat at 349 billion yen, as some of the G8.6 board OLED investment is expected to be carried over to the next fiscal year. For fiscal 2027, we forecast sales of 429 billion yen, an increase of 23%, combining carryover from the previous year for OLED and investments driven by larger TV screen sizes.

- (1) Forecast period                      Three years from fiscal year 2025 to 2027 (FY2025: From April 2025 to March 2026)
- (2) Forecast items                        Sales of Japanese-made semiconductor manufacturing equipment and sales for the Japanese market
- Sales of Japanese-made FPD manufacturing equipment
- (3) Forecast background

### **(Semiconductor Manufacturing Equipment)**

According to WSTS (World Semiconductor Trade Statistics) in December 2025, the global semiconductor market is projected to reach 772 billion US dollars in 2025, an increase of 22.5% from the previous year. This marks the second consecutive year of record-breaking growth, driven by strong expansion in memory and logic products. Similarly, strong growth in memory and logic is anticipated for 2026, driven by data center investments by major IT companies and strong growth in memory and logic products, with the market projected to reach 976 billion US dollars, an increase of 26.3, bringing the trillion-dollar mark within reach.

The performance of memory companies has largely continued to rise since bottoming out in the first

quarter of 2023 (January to March), with operating profit margins remaining at high levels. Concerning DRAM, the shortage of facilities and utilities themselves means that building capacity, including purchasing and bringing up equipment, is increasingly unable to keep pace with the immediate AI demand. Demand for AI servers remains robust, while in some cases, prioritizing HBM supply is making it difficult to allocate spare production capacity to consumer-grade general-purpose DRAM like DDR5.

As for NAND, in addition to the expansion of demand for AI data centers, the combined effect of a supply shortage of HDDs has led to a surge in demand for SSDs for data centers. Due to uncertainty about the continuity of demand and the priority given to investment in high-profit margin DRAM, large-scale investment expansion is not seen at this stage, but ASP is on an upward trend, and investment is expected to accelerate as profitability improves in the future.

Regarding logic, in addition to general-purpose GPUs, demand is growing for ASICs, which are specialized for specific applications and achieve high-speed processing and low power consumption at low cost, for AI chips used in data centers. Logic for smartphones and PCs will also need to continue to be further miniaturized and heterogeneous integration in order to perform high-speed AI processing while reducing power consumption on the edge side.

AI will continue to drive semiconductor market growth in the future. Based on current "LLMs" (large-scale language models), AI is expected to evolve into "Agent AI," capable of planning, decision-making, and action, and "Physical AI," capable of recognizing and understanding the real world and acting in physical space. Training more advanced models and executing their inference will require even more computing power. This will drive ever-increasing demand for higher performance, lower power consumption, and larger capacity semiconductors. This will drive cutting-edge investments in technological advances, such as further evolution of GAA architectures, higher stacking of memory such as HBM, and adoption of BSPDN (Back Side Power Delivery Network).

In particular, in order to solve the problem of the so-called "memory wall," where improvements in memory bandwidth become a bottleneck compared to improvements in logic performance, the emergence of new memory technologies is expected, such as the expansion of HBM capacity and acceleration of generation transitions through the miniaturization of DRAM and an increase in the number of layers, as well as HBF (High Bandwidth Flash) using high-capacity NAND.

The global semiconductor market was initially forecast to grow from \$630.5 billion in 2024 to \$1 trillion in 2030, but it is now increasingly likely that the \$1 trillion milestone will be reached significantly earlier than previously anticipated. Semiconductor manufacturing equipment is also expected to show high growth over the medium term.

### **(FPD Manufacturing Equipment)**

The business environment surrounding FPD manufacturing equipment has shown signs of improvement since the second quarter of 2023 (April to June), but the profit level remains low except

for two Korean companies. While LCD panel shipments for TVs in 2025 are expected to see a slight decrease in volume, the average size is projected to increase, leading to growth in shipment value and area.

The trend toward larger average screen sizes is becoming particularly pronounced in China, and in the medium term, a shift from the current mainstream 65-inch models to 75-inch and 85-inch models is also expected to progress.

In South Korea and China, capital investment for manufacturing OLEDs for IT products using G8.6 boards has already begun. Going forward, OLED panel adoption will progress sequentially from tablets (11.1-inch, 13-inch, etc.), to laptop PCs (13.6-inch, 14.2-inch, 15.3-inch, 16.2-inch, etc.).

However, the most recent situation shows that the overall adoption of OLED panels in IT products has been slightly delayed compared to initial plans, due to factors such as the prioritization of AI functionality enhancements and the surge in memory costs. Regardless, IT panels are significantly larger than smartphone panels (6.1 to 6.9 inches), with each unit covering an area 6 to 7 times greater. The outlook that demand for equipment will grow as OLED adoption progresses remains unchanged.

Sales of Japanese-made FPD manufacturing equipment are projected to see slight growth or remain flat from fiscal 2025 to fiscal 2026, followed by a full-fledged recovery starting in fiscal 2027.

#### (4) Forecast results

##### ***【Sales forecasts for semiconductor/FPD manufacturing equipment made in Japan】***

For fiscal 2025, we forecast overall sales of 5.26 trillion yen, an overall 3% increase, assuming that semiconductor manufacturing equipment will increase by 3%, and sales of FPD manufacturing equipment will increase by 3%. For fiscal 2026, semiconductors are projected to increase by 12%, while FPDs are expected to remain flat at  $\pm 0\%$ . Overall, the market is forecast to grow with overall sales of 5.85 trillion yen, an overall 11.2% increase. For fiscal 2027, semiconductor equipment sales are projected to increase by 2% while FPDs are expected to ramp up by 23%, as we forecast overall sales of 6.04 trillion yen, an overall increase of 3.3%.

##### ***【Sales forecasts for semiconductor manufacturing equipment made in Japan】***

In fiscal year 2025, although investment in some logic, automotive, and power semiconductors will remain sluggish, sales are forecast to increase 3% year-on-year to 4.9 trillion yen due to the full-scale start of 2nm investment by Taiwanese foundries and solid DRAM investment, mainly HBM. The year-on-year growth rate for fiscal year 2024 was up 29%, so although the growth rate is low, sales will remain at a high level.

For fiscal 2026, in addition to continued expansion in DRAM investment, investment in cutting-edge logic for AI servers is expected to expand, we forecast a 12% increase to 5.50 trillion yen. For fiscal 2027, AI-related demand is expected to remain high, leading to a forecast of 5.61 trillion yen,

a 2% increase.

The projections for all fiscal years 2025, 2026, and 2027 have all been revised upward from the forecast amounts announced last July.

***【Sales forecasts for semiconductor manufacturing equipment in the Japanese market】***

In fiscal 2025, investment in automotive and power semiconductors fell sharply in fiscal 2025. Although investments utilizing cutting-edge technologies were made in NAND flash and DRAM, overall growth is expected to remain mild, as we forecast a 5% increase to 1.31 trillion yen.

Strong memory investment is expected in fiscal 2026 as well, we forecast a 5% increase to 1.38 trillion yen. For fiscal 2027, we forecast a 10% increase to 1.52 trillion yen, due to the addition of second-phase investments by major foundries and mass production investments for 2nm logic.

***【Sales forecasts for FPD manufacturing equipment made in Japan】***

For fiscal 2025, investment in OLED panels for IT products using G8.6 boards began, leading to our forecast of 349 billion yen, a 3% increase. For fiscal 2026, LCD investment is expected to grow against the backdrop of larger average TV panel sizes. In contrast, G8.6 OLED investment is projected to proceed at a slower pace than anticipated, resulting in a flat figure of 349 billion yen.

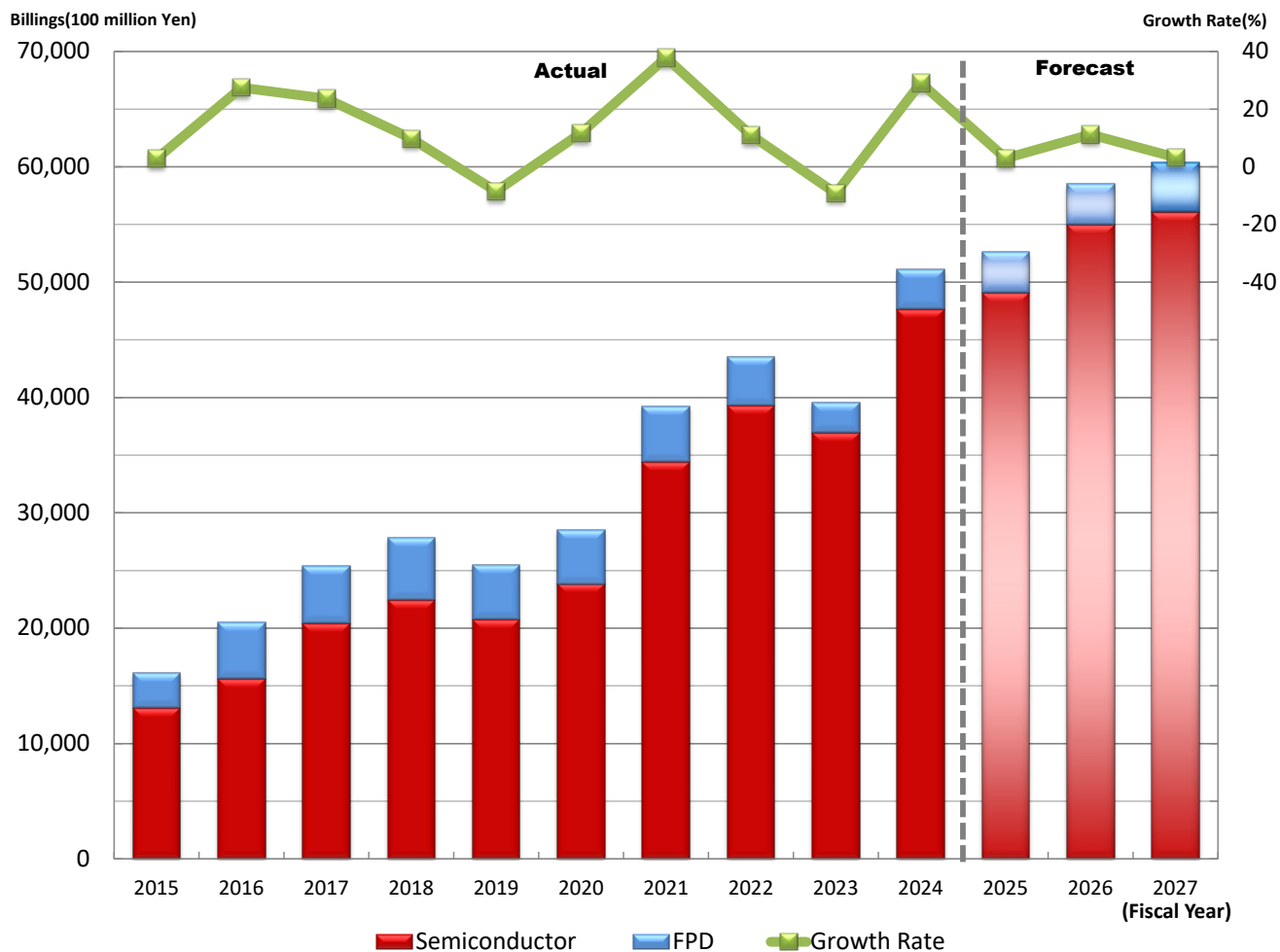
For fiscal 2027, multiple G8.6-class OLED investments, including carryovers from fiscal 2026, are anticipated. Combined with LCD investments driven by the trend toward larger average panel sizes for TVs, this will result in a 23% increase in our forecast to 429 billion yen.

## January 2026 Forecast for Semiconductor and FPD Manufacturing Equipment

### ■ 1. Semiconductor and FPD Manufacturing Equipment

#### 【Forecast for Japanese Equipment Billing】

\* "Japanese Equipment Billing " = Japanese manufacturers Domestic and Oversea Billing.



(CAGR : 2024-2027)

Fiscal Year	Actual										Forecast			CAGR
	2015	2016	2017	2018	2019	2020	2021	2022	2023	2024	2025	2026	2027	
Semiconductor	13,089	15,642	20,436	22,479	20,730	23,835	34,430	39,275	36,976	47,681	49,111	55,004	56,104	5.8%
FPD	2,993	4,857	4,916	5,364	4,758	4,638	4,809	4,282	2,577	3,388	3,490	3,490	4,292	
Total (100 million yen)	16,082	20,499	25,352	27,843	25,488	28,473	39,239	43,556	39,553	51,069	52,601	58,494	60,397	
Growth Rate (%)	2.8	27.5	23.7	9.8	-8.5	11.7	37.8	11.0	-9.2	29.1	3.0	11.2	3.3	

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\* FPD statistics participating companies have changed since FY2019.

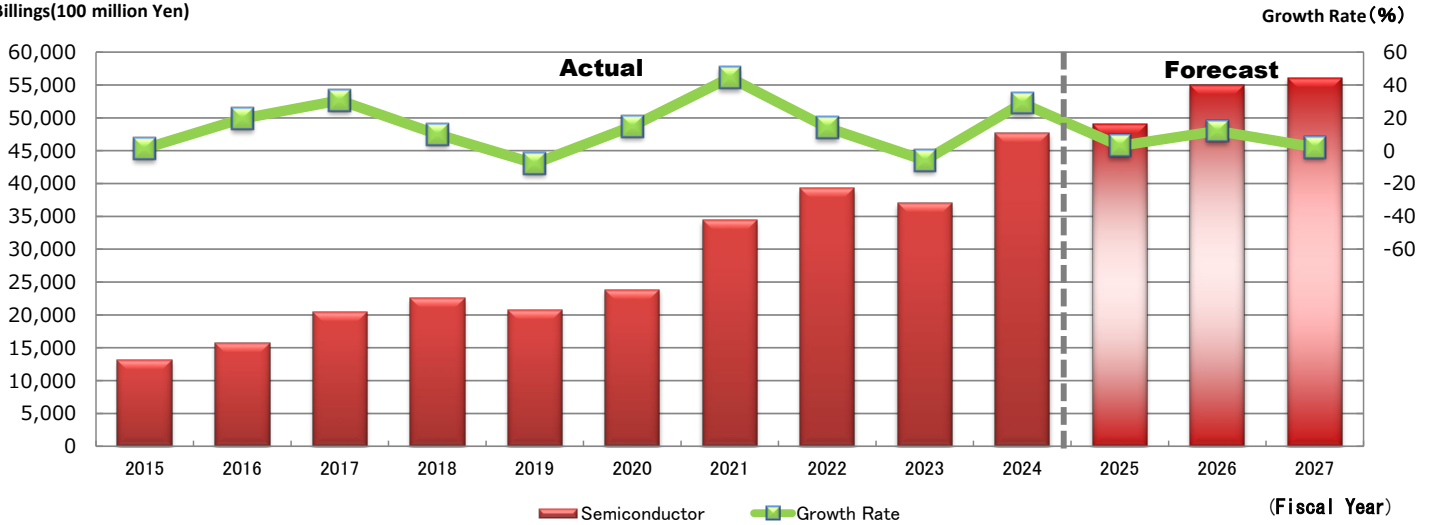
\* The names and amounts of the companies participating in the statistics are not disclosed.

## January 2026 Forecast for Semiconductor and FPD Manufacturing Equipment

### ■ 2. Semiconductor Manufacturing Equipment 【Forecast for Japanese Equipment Billing】

\* "Japanese Equipment Billing" = Japanese manufacturers Domestic and Oversea Billing.

Billings(100 million Yen)



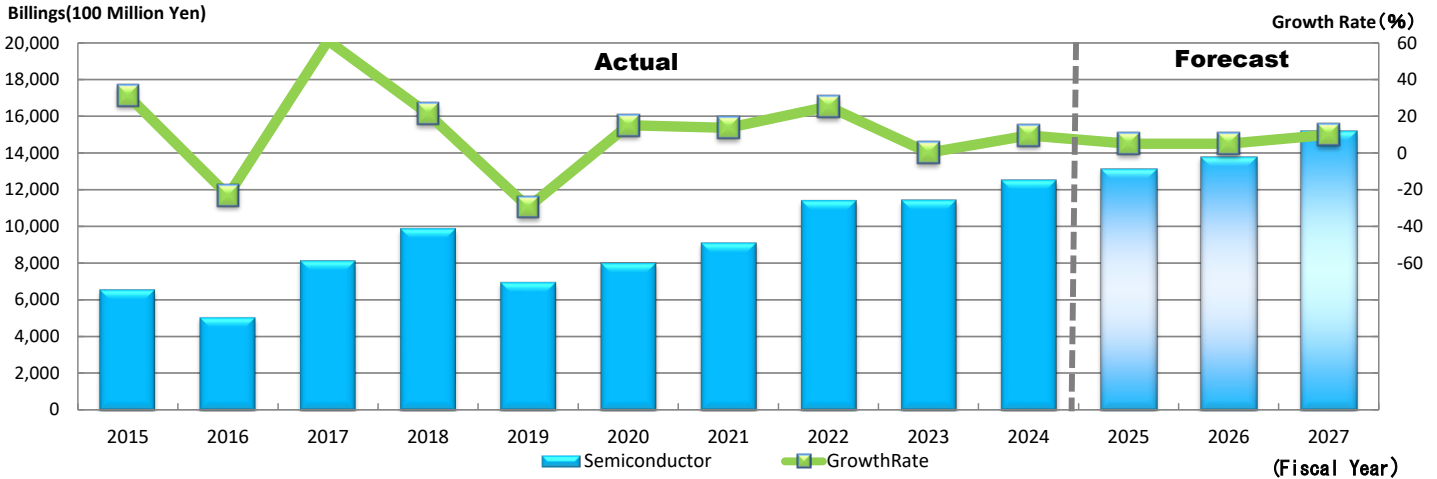
(CAGR : 2024-2027)

	Actual										Forecast			
Fiscal Year	2015	2016	2017	2018	2019	2020	2021	2022	2023	2024	2025	2026	2027	CAGR
Total (100 million yen)	13,089	15,642	20,436	22,479	20,730	23,835	34,430	39,275	36,976	47,681	49,111	55,004	56,104	
Growth Rate (%)	1.3	19.5	30.6	10.0	-7.8	15.0	44.4	14.1	-5.9	29.0	3.0	12.0	2.0	5.6%

### 【Forecast for Japanese Market Billing】

\* "Japanese Market Billing" = Domestic Billing of Japanese and Foreign manufacturers.

Billings(100 Million Yen)



(CAGR : 2024-2027)

	Actual										Forecast			
Fiscal Year	2015	2016	2017	2018	2019	2020	2021	2022	2023	2024	2025	2026	2027	CAGR
Total (100 million yen)	6,562	5,047	8,138	9,878	6,961	8,009	9,103	11,412	11,432	12,521	13,147	13,805	15,185	
Growth Rate (%)	31.2	-23.1	61.3	21.4	-29.5	15.1	13.7	25.4	0.2	9.5	5.0	5.0	10.0	6.6%

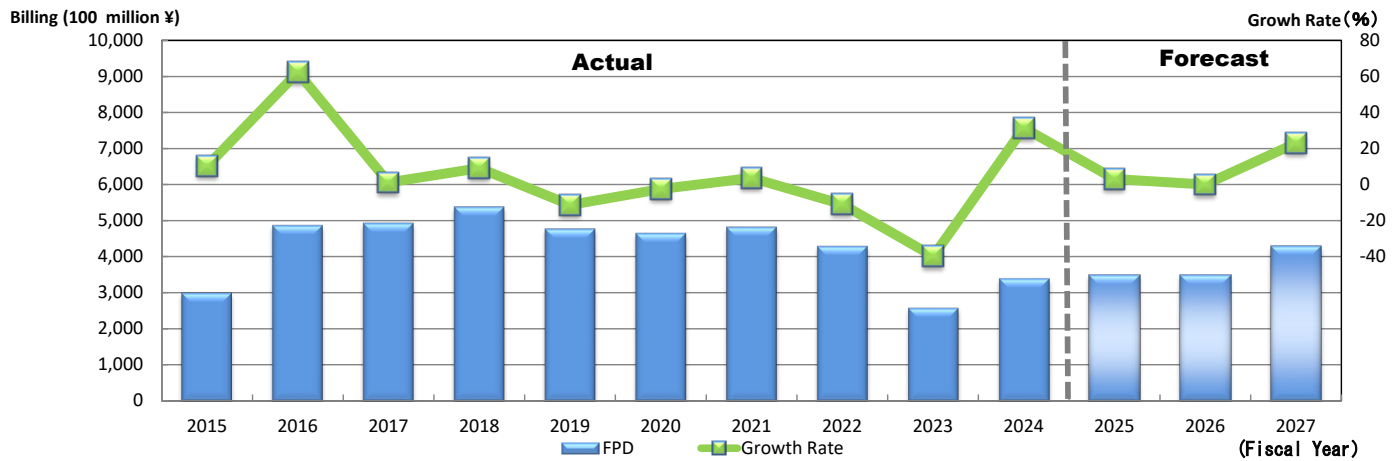
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# January 2026 Forecast for Semiconductor and FPD Manufacturing Equipment

## ■3. FPD Manufacturing Equipment

### 【Forecast for Japanese Equipment Billing】

\* "Japanese Equipment Billing " = Japanese manufacturers Domestic and Oversea Billing.



Fiscal Year	Actual										Forecast			CAGR
	2015	2016	2017	2018	2019	2020	2021	2022	2023	2024	2025	2026	2027	
Total (100 million yen)	2,993	4,857	4,916	5,364	4,758	4,638	4,809	4,282	2,577	3,388	3,490	3,490	4,292	
Growth Rate (%)	10.2	62.3	1.2	9.1	-11.3	-2.5	3.7	-11.0	-39.8	31.4	3.0	0.0	23.0	8.2%

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